



Steelix

2U24Bay Storage Server System

Highlights

- Efficient Computing Performance with Revolutionary Single Socket Solution
- High-Density 2U Form Factor Supports 24x LFF HDD Bay
- Flexible and Scalable I/O Options
- Optimized Serviceability



Steelix, a high-density storage server powered by AMD EPYC[™] 7003 Series Processor, features 24x 3.5" HDDs and 4x 2.5" SSDs hot-plug drives and hot-swappable fan module with easy serviceability in a simple 2U enclosure. Steelix offers efficient computing power, storage capacity, and flexible I/O expansibility. This enables optimized workload for synergy across network, computing and storage. Provides a higher virtualized workload throughput and number of VM density and helps to adapt quickly to changing business computing needs.

Enhanced Performance and Advanced Security

Steelix is an industry-leading storage server that supports the new 3rd Gen AMD EPYC[™] processor, with TDP of up to 280W. It provides exceptional performance with up to 64 cores, 128 lanes of PCle Gen4 connectivity, and up to 4TB of memory across 16 DIMM slots. In addition, it has up to 32MB L3 cache per 8 core, helping accelerate memoryintensive workloads.

The embedded x86 silicon-level data enables Steelix to offer AMD Infinity Guard features, including Secure Memory Encryption (SME), which help secure the boot process, encrypt the entire main memory, and Secure Encrypted Virtualization (SEV), which can secure virtualized environments and container. Steelix is well guarded, which helps decrease potential attack surfaces and enable better protection of software and data.



Front View



Rear View





Ultra-Density and Great Scalability

Steelix offers a variety of hot-pluggable hybrid flash array choices within the 2U form factor. It's composed of 24 LFF HDD bays and 4 rear side SSD bays and provides multiple storage options for greater flexibility and scalability. Including NVMe support in the rear for a caching layer, 1x M.2 via interposer connection, and a variety of storage mezzanine cards

Besides, it supports up to 4TB of DDR4 memory. By hosting 4x PCle slots (two x8 for Low profile + two x16 for FHHL) with riser cards and 1 PCle x16 lanes for OCP 3.0, Steelix is an ideal hybrid system for warm storage and applicable for further storage applications. Optimizing the ratio of SSDs and HDDs can highly accelerate IOPS and throughput performance while the excellence of storage capacity is delivered.

Flexible Network Configuration

Steelix offers an OCP NIC mezzanine option, ranging from 10G Ethernet to 100G (optical or Base-T, compatible with OCP 3.0). This allows high-speed performance and I/O flexibility, catering to suitable demands of different application procedures.

Steelix | Storage Server

General Purpose / Warm Storage
2U24Bay rack mount with slide rail for HDD tray W x H x D: 447x 87x 890 mm (17.60x 3.43x 35.04 inch)
One AMD EPYC [™] 7003 Series Processor; Up to 64 cores TDP : Up to 280W
8 channels DDR4 with ECC up to 3200 MHz 16 DIMMs / 8 memory channels (2DPC) DIMM Type: RDIMM,LRDIMM, NV-DIMM 4TB/Socket (256GB DIMMs)
Front HDD Tray: 24x 3.5" SAS/SATA hot-plug drives Rear HDD BP: Support up to 4x U.2 NVMe / SATA SSDs Internal:1x SATA M.2 with Interposer
2x PCIe x8 slots for Low Profile PCIe add-in cards (HBA/RAID) 2 x PCIe x16 slots for FHHL PCIe add-in cards
Support 10GbE/25GbE/40GbE/100GbE OCP Mezz or Standard PCIe card
Option1: Inventec SAS Mezz w/ SAS3224- 24i Option2: SAS9305-24i (12Gb/s)
IPMI 2.0 compliant+ KVM with Dedicated LAN
TPM2.0 (optional)
1+1 redundancy 800W/1300W/1600W (100-220VAC & 240V HVDC) Platinum
N+1 redundancy, 5x 6056 hot-swap fan

About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

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